

Another aspect of the present is the transducer-supporting structure, characterized in that said thermal coupling member has an elastic restoring force, and is in contact with said transducer.

Please replace the paragraph beginning at page 8, line 3 with the following:

Still another aspect of the present invention is the transducer-supporting structure, characterized in that said transducer is an electromagnetic transducer.

Please replace the paragraph beginning at page 8 line 7 with the following:

Yet still another aspect of the present invention is the transducer-supporting, characterized in that said transducer is an electro-optical transducer.

Please replace the paragraph beginning at page 8, line 11 with the following:

Still yet another aspect of the present invention is a transducer-supporting structure, characterized in that said structure at least comprises:

Please replace the paragraph beginning at page 9, line 9 with the following:

A further aspect of the present is a transducer-supporting structure, characterized in that said structure at least comprises:

Please replace the paragraph beginning at page 10, line 7 with the following:

A still further aspect of the present invention is a transducer-supporting structure, characterized by at least comprising:

Please replace the paragraph beginning at page 10, line 16 with the following:

A yet further aspect of the present invention is the transducer-supporting, characterized in that said transducer is an electromagnetic transducer.

Please replace the paragraph beginning at page 11, line 1 with the following:

A still yet further aspect of the present invention is the transducer-supporting structure, characterized in that said transducer is an electro-optical transducer.

Please replace the paragraph beginning at page 18, line 3 with the following:

Reference numeral 15 denotes a viscous liquid material with relatively high thermal conductivity, such as a gel-form heat conductive material. For example, silicone grease is preferably selected as the heat conductive material 15. The heat conductive material 15 is stuck in the vicinity of a contact region of the thermally coupling contact portion 13d and the magnetic core 2.

Please replace the paragraph beginning at page 19, line 17 with the following:

FIG. 7 shows an essential part of a transducer-supporting structure in accordance with a third embodiment of the present invention. A slider 1, a magnetic core 2, a coil 4, and a disk 10 are the same as those elements of the first embodiment. Although the whole of a suspension is not shown in FIG. 7, the suspension is approximately the same as the suspension 3 of the first embodiment, and a gimbal portion 23b is the same as the gimbal portion 3b of the first embodiment.

Please replace the paragraph beginning at page 20, line 1 with the following:

A tongue 23c is approximately the same as the tongue 103c of the conventional example, and is connected to the slider 1. However, the tongue 23c differs from the tongue 103c in that it extends longer toward the magnetic core 2 than the tongue 103c. Reference numeral 25 denotes a gel-form heat conductive material with relatively high thermal conductivity. In this embodiment, the heat conductive material 25 functions as a thermal coupling member, and is applied to the magnetic core 2, the tongue 23c, and a gap there between.

Please replace the paragraph beginning at page 22, line 6 with the following:

The following will be a description of the operation of the transducer-supporting structure constructed as described above.

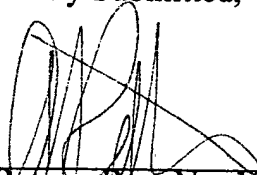
Please replace the paragraph beginning at page 23, line 3 with the following:

The semiconductor laser 8a generates a large amount of heat relative to the volume thereof. However, since the suspension 33 is connected to the semiconductor laser 8a, the heat can be dissipated through the suspension 33, so that a rise in temperature of the semiconductor laser 8a can be neglected. For this reason, the life of the semiconductor laser 8a increases. Also, a rise in temperature of the whole of the integrated optical system 8 can be prevented. Therefore, even in the case where an element whose shape is wavelength dependent such as a hologram element is used, the influence of thermal expansion can be neglected, so that the reliability and hostile-environment resistance are improved. Also, a hologram element formed of a resin sensitive to thermal expansion can be used, which achieves a reduction in cost.

Please replace the paragraph beginning at page 24, line 7 with the following:

A magnetic core 42 has the whole shape that is approximately the same as that of the magnetic core 2 of the first embodiment, but differs from the magnetic core 4 in that the magnetic core 42 has a heat dissipating portion 42b as heat dissipating means.

Respectfully Submitted,



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Dated: November 19, 2001

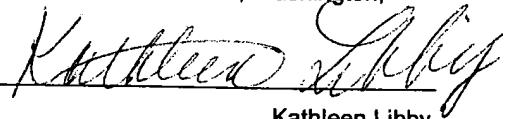
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Kathleen Libby